

[illegible][illegible]

Examiner Signature	<i>rac hquyue</i>	Date Considered	10/31/05
-----------------------	-------------------	--------------------	----------

*Applicant's unique citation designation number (optional). *See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. *Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). *For Japanese patent documents, the indication of the year of reign of the Emperor must precede the serial number of the patent document. *Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 18 if possible. *Applicant is to place a check mark here if English language Translation is attached.

Send To: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Complete if Known	
				Application Number	10/799,204
Sheet 2 of 3				Filing Date	03/11/2004
				First Named Inventor	Joan K. Vrtis
				Art Unit	3729
				Examiner Name	Tai van Nguyen
				Attorney Docket Number	42P13111D

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No.†	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T‡
TN		BATH, J., Selectron Corp., Lead Free Process Group Update, National Electronics Manufacturing Initiative, Jan. 17, 2001.	
		DEBIASE, JOSEPH D., Organic Solderability Preservatives: Benzotriazoles And Substituted Benzimidazoles, Enthone-OMI Inc., Conference Proceedings; Surface Mount International Conference, September 10, 1996, Abstract page downloaded from Surface Mount Technology Association, SMTA Headquarters - 5200 Willson Road, Suite 215, Edina, Minnesota 55424. 1 page.	
		DEBIASE, JOSEPH D., Organic Solderability Preservatives: Benzotriazoles And Substituted Benzimidazoles, Proceedings Of the SMTA, 1996, Enthone-OMI Inc., New Haven, Connecticut, pages 763-776.	
		HART, K., ET AL., DFE Study Gives Alternative Finishes the Green Light, PC FAB, Oct. 2000.	
		JOHNSON, R.W., ET AL, Thermal Cycle Reliability of Solder Joints to Alternate Plating Finishes, paper from Auburn University, 2000.	
		MORAWSKA, Z, ET AL., Lead-Free Solderability Preservative Coatings for PCBs, Advanced Microelectronics, v. 28, no. 3, May/June 2001.	
TN		PARQUET, D., ET AL., OSP: The High Performance Surface Finish, Electronic Interconnect Conference, 1997.	

Examiner Signature	<i>Tai van Nguyen</i>	Date Considered	10/31/05
--------------------	-----------------------	-----------------	----------

*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication.

†Applicant's unique citation designation number. ‡Applicant is to place a check mark here if English language Translation is attached.

Based on PTO/SB/08B (08-03) as modified by Blakey, Solokoff, Taylor & Zafman (w/ 08/11/2003).
Send To: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Complete if Known		
				Application Number	10/799,204	
Sheet		3	of	3	Filing Date	03/11/2004
					First Named Inventor	Joan K. Vrtis
					Art Unit	3729
					Examiner Name	Tai van Nguyen
					Attorney Docket Number	42P13111D

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No.*	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T*
TN		ROMM, D., ET AL., Evaluation of Ni/Pd-Finished ICs with Lead Free Solder Alloys, Texas Instruments Application Report SZZA024, Jan. 2001.	
		SOLBERG, V., Impact of PCB Surface Finish on SMT Assembly Process Yield, Application Note from Tesser Corp.	
		SYED, A., Amkor Technology Corp., Surface Mount Requirements for Advanced Packaging Solutions, 2000.	
		WENGENROTH, KARL, ET AL., OSPS: Addressing Future Surface Finishing Needs, Enthone-OMI, Conference Proceedings, Surface Finishes Forum Conference, May 4, 2000, Abstract page downloaded from Surface Mount Technology Association, SMTA Headquarters - 5200 Willson Road, Suite 215, Edina, Minnesota 55424, 1 page.	
		Double Sided 4Mb SRAM Coupled Cap PBGA Card Assembly Guide, IBM Application Note, Feb. 1998.	
TN		Kester Solder Paste for Surface Mount and General Electronics Assemblies, Online Catalog of Preferred Products, 2001.	

Examiner Signature	<i>Tai van Nguyen</i>	Date Considered	10/31/05
--------------------	-----------------------	-----------------	----------

*Examiner: Initial reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication.

*Applicant's unique citation designation number. *Applicant is to place a check mark here if English language Translation is attached.

Based on PTO/SB/08B (08-03) as modified by Blakely, Solokoff, Taylor & Zafman (wtr) 08/11/2003.
Send To: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450